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Amendment to the Claims:

        1-4 (canceled)


        5 (currently amended):  A method of qualifying a
process tool comprising steps of:
        (a) finding a plurality of pre-scan defect locations on a
surface of a semiconductor wafer;
        (b) subjecting the semiconductor wafer to processing by a
process tool after step (a);
        (c) finding a plurality of post-scan defect locations on
the surface of the semiconductor wafer after step (b);
        (d) calculating which defects were added by the process
tool from the pre-scan defect locations and the post-scan
defect locations;
        (e) displaying a scatter plot of a point representative
of a total number of defects added by the process tool to the
semiconductor wafer; and
        (f) The method of Claim 3 further comprising a step of
selecting the point on the scatter plot to initiate a display
of one of a pre-test wafer map, a post-test wafer map, and an
added defect map of defects added by the process tool to the
semiconductor wafer.


        6 (previously presented):  The method of Claim 5
further comprising a step of associating a spatial signature
of added defects from the added defect map with a process tool
malfunction.


        7 (canceled)


        8 (currently amended):  A method of qualifying a

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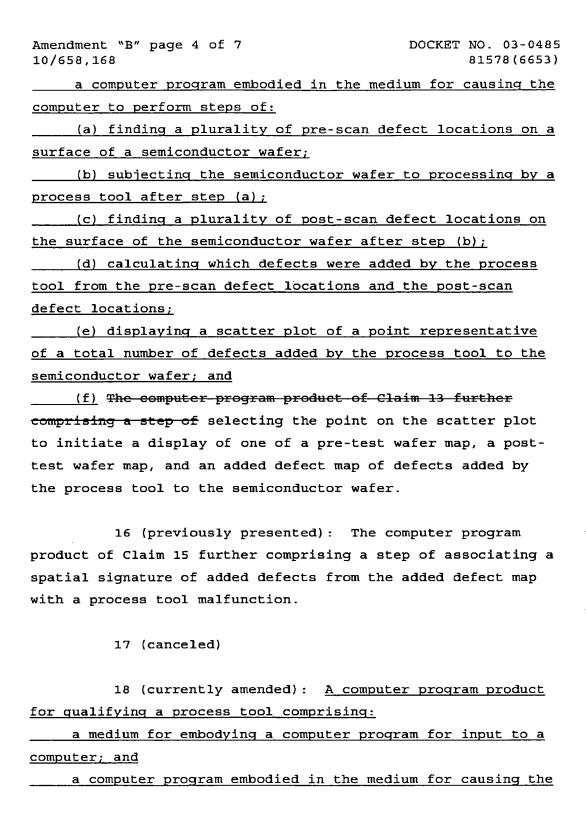10/658,168                                              81578(6653)

process tool comprising steps of:

     (a) finding a plurality of pre-scan defect locations on a
surface of a semiconductor wafer;

     (b) subjecting the semiconductor wafer to processing by a
process tool after step (a);

     (c) finding a plurality of post-scan defect locations on
the surface of the semiconductor wafer after step (b);

     (d) calculating which defects were added by the process
tool from the pre-scan defect locations and the post-scan
defect locations by comparing a distance between a first point
corresponding to a defect location in a first list of pre-test
defect locations and a second point corresponding to a defect
location in a second list of post-test defect locations with a
registration tolerance; and

     (e) marking ~~The method of Claim 7 wherein~~ the defect
location in the second list ~~corresponding to the second point
is marked~~ as a non-adder when [[if]] the distance is less than
the registration tolerance.


          9 (original):  The method of Claim 8 wherein the
first list and the second list are sorted by X-coordinate.


          10 (original):  The method of Claim 9 wherein defect
locations in the first list and the second list having
identical X-coordinates are further sorted by Y-coordinate.


          11-14 (canceled)


          15 (currently amended):  A computer program product
for qualifying a process tool comprising:

     a medium for embodying a computer program for input to a
computer; and

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     a computer program embodied in the medium for causing the
computer to perform steps of:

     (a) finding a plurality of pre-scan defect locations on a
surface of a semiconductor wafer;

     (b) subjecting the semiconductor wafer to processing by a
process tool after step (a);

     (c) finding a plurality of post-scan defect locations on
the surface of the semiconductor wafer after step (b);

     (d) calculating which defects were added by the process
tool from the pre-scan defect locations and the post-scan
defect locations;

     (e) displaying a scatter plot of a point representative
of a total number of defects added by the process tool to the
semiconductor wafer; and

     (f) ~~The computer program product of Claim 13 further
comprising a step of~~ selecting the point on the scatter plot
to initiate a display of one of a pre-test wafer map, a post-
test wafer map, and an added defect map of defects added by
the process tool to the semiconductor wafer.


     16 (previously presented):  The computer program
product of Claim 15 further comprising a step of associating a
spatial signature of added defects from the added defect map
with a process tool malfunction.


     17 (canceled)


     18 (currently amended):  A computer program product
for qualifying a process tool comprising:

     a medium for embodying a computer program for input to a
computer; and

     a computer program embodied in the medium for causing the

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computer to perform steps of:

        (a) finding a plurality of pre-scan defect locations on a
surface of a semiconductor wafer;

        (b) subjecting the semiconductor wafer to processing by a
process tool after step (a);

        (c) finding a plurality of post-scan defect locations on
the surface of the semiconductor wafer after step (b);

        (d) calculating which defects were added by the process
tool from the pre-scan defect locations and the post-scan
defect locations by comparing a distance between a first point
corresponding to a defect location in a first list of pre-test
defect locations and a second point corresponding to a defect
location in a second list of post-test defect locations with a
registration tolerance; and

        (e) marking ~~The computer program product of Claim 17~~
~~wherein~~ the defect location in the second list ~~corresponding~~
~~to the second point is marked~~ as a non-adder when [[if]] the
distance is less than the registration tolerance.


        19 (original):  The computer program product of
Claim 18 wherein the first list and the second list are sorted
by X-coordinate.


        20 (original):  The computer program product of
Claim 19 wherein defect locations in the first list and the
second list having identical X-coordinates are further sorted
by Y-coordinate.